

JEDEC SOLID STATE
PRODUCT OUTLINE
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THIS *REGISTERED OUTLINE* HAS BEEN PREPARED BY THE JEDEC JC-11 COMMITTEE
AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY;
CHANGES ARE LIKELY TO OCCUR

TITLE PLASTIC BOTTOM GRID
ARRAY BALL, 0.60 MM X 0.50 MM PITCH
RECTANGULAR FAMILY PACKAGE

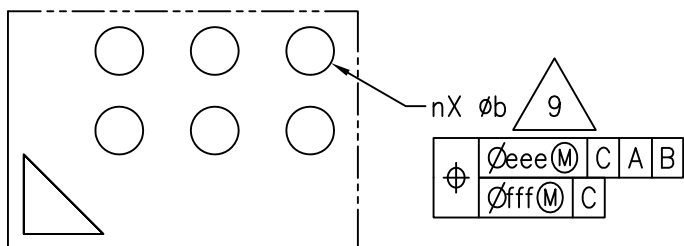
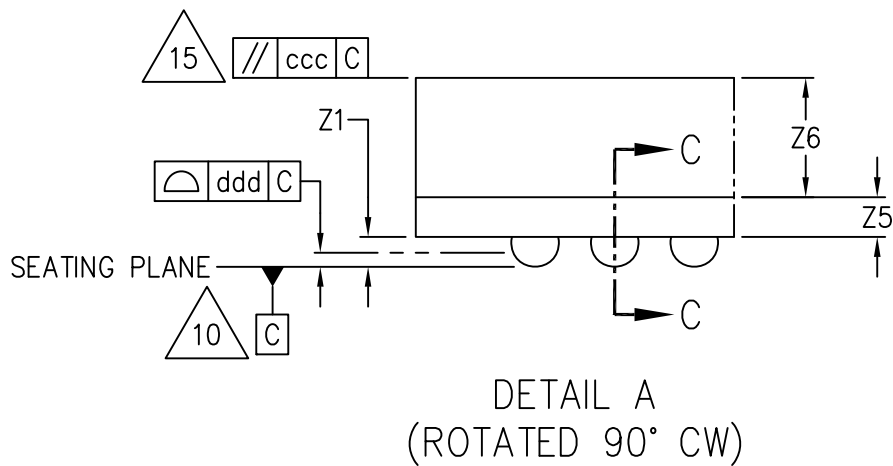
PACKAGE DESIGNATOR
PBGA-B#[#]
_l0p5...

NUMBER
MO-363

ISSUE
A

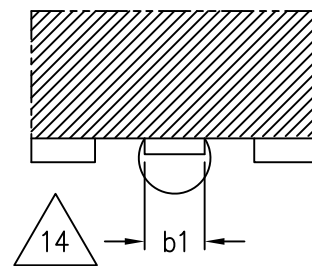
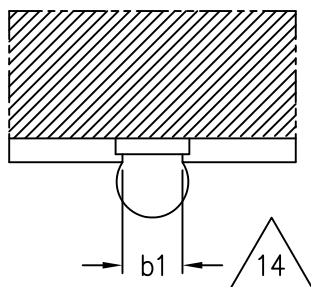
DATE
JUL 2024

SHEET
1 OF 8



TYPE 1 – SMD
(SOLDER MASK DEFINED)

TYPE 2 – NSMD
(NON SOLDER MASK DEFINED)



SECTION C-C

TABLE 1

COMMON DIMENSIONS		
SYMBOL		
Z		PACKAGE SPECIFIC
Z2	b(NOM) = 0.300	$Z2(MAX) = Z(MAX) - Z1$
Z5		OPTIONAL – PACKAGE SPECIFIC
Z6		OPTIONAL – PACKAGE SPECIFIC
eX		0.60 BASIC
eY		0.50 BASIC
NOTES		1, 2, 8
REF		11–1066
ISSUE		A


TABLE 2

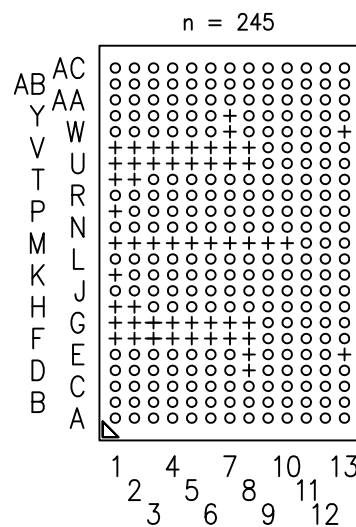
COMMON DIMENSIONS						
SYMBOL	(b) SOLDER BALL DIAMETER					
	MIN	NOM	MAX	MIN	NOM	MAX
Z1	PACKAGE SPECIFIC	----	----	----	----	----
b	0.225	0.30	0.375	----	----	----
b1	TYPE1	0.20	----	----	----	----
	TYPE2	0.20	----	----	----	----
NOTES	1, 2, 9, 17			—		
REF	11–1066			—		
ISSUE	A			—		

TABLE 3

TOLERANCE OF FORM AND POSITION				
SYMBOL	PACKAGE TYPE	VALUE		
		øb NOM = 0.300	----	----
aaa	----	0.10	----	----
ccc	ENCAPSULATED	0.20	----	----
ddd	----	0.08	----	----
eee	ENCAPSULATED	0.15	----	----
fff	----	0.05	----	----
NOTES		2	—	—
REF		11–1066	—	—
ISSUE		A	—	—

TABLE 4

øb = 0.300 NOMINAL													
NEW VARIATION	X BASIC	Y BASIC	X1 BASIC	Y1 BASIC	MX	MY	SX BASIC	SY BASIC	n	N	TERMINAL PATTERN	REF	ISSUE
 PBGA-B245[299]_I0p5- R8p2x12p4Z#-C0p30Z#	8.20	12.40	7.20	11.00	13	23	0.00	0.00	245	299	A	11-1066	A
NOTES	2	2	2	2	5	5	2, 12	2, 12	6, 13	6	13		



TERMINAL PATTERN A



+ = DEPOPULATED TERMINAL POSITIONS

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5–2009.
THIS OUTLINE CONFORMS TO JEP95, SECTION 4.5.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
- 3 SOLDER BALL POSITION DESIGNATION PER JEP95 SECTION 3, SPP–010.
4. eX REPRESENTS THE SOLDER BALL GRID PITCH IN X DIRECTION.
eY REPRESENTS THE SOLDER BALL GRID PITCH IN Y DIRECTION.
5. MX AND MY REPRESENT THE MAXIMUM MATRIX SIZE CORRESPONDING TO THE
X AND Y DIRECTIONS RESPECTIVELY.
6. n REPRESENTS THE ACTUAL NUMBER OF SOLDER BALLS AFTER DEPOPLUATION.
N REPRESENTS THE MAXIMUM NUMBER OF SOLDER BALLS FOR A FULL MATRIX, MX X MY.

7 A FULLY POPULATED 22 X 32 MATRIX SIZE IS SHOWN FOR ILLUSTRATION ONLY.

8 DIMENSION Z INCLUDES STAND–OFF HEIGHT Z1, PACKAGE BODY THICKNESS
AND LID HEIGHT, BUT DOES NOT INCLUDE ATTACHED FEATURES, e.g., EXTERNAL
HEATSINK. AN INTEGRAL HEATSLUG IS NOT CONSIDERED AN ATTACHED FEATURE.

9 DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO
PRIMARY DATUM C.

10 PRIMARY DATUM C (SEATING PLANE) IS DEFINED BY THE PLANE ESTABLISHED BY THE
CONTACT POINTS OF THREE OR MORE SOLDER BALLS THAT SUPPORT THE DEVICE WHEN
IT IS PLACED ON TOP OF A PLANAR SURFACE.

11 THE Z1 TERMINAL CORNER MUST BE IDENTIFIED ON BOTH THE BOTTOM AND TOP SIDES
OF THE PACKAGE, THE IDENTIFICATION FEATURE CAN BE MADE USING INK, METALIZED
MARKINGS, IDENTATIONS, OR OTHER FEATURES.

12 DIMENSIONS SX AND SY ARE MEASURED WITH RESPECT TO DATUMS A AND B
AND DEFINE THE POSITION OF THE CENTER SOLDER BALLS.
WHEN THERE IS AN ODD NUMBER OF SOLDER BALLS, SX OR $SY = 0.00$.
WHEN THERE IS IS AN EVEN NUMBER OF SOLDER BALLS, $SX = eX/2$ OR $SY = eY/2$.

13 SOLDER BALL DEPOPULATION IS ALLOWED. DEPOPULATION IS THE OMISSION
OF BALLS FROM A FULL MATRIX (MX X MY).

14 THE SOLDERABLE SURFACE MAY BE DEFINED BY AN OPENING IN THE SOLDER RESIST LAYER
(TYPE 1) OR BY THE SIZE OF A METALIZED PAD (TYPE 2). IT MAY BE ELLIPITACL PROVIDED
THE RATIO OF THE MAJOR TO MINOR AXES IS NO GREATER THAN 2/1, AND THE SURFACE
AREA IS NO LESS THEN THE MINIMUM FOR A CIRCULAR PAD. FOR TYPE 2 DESIGNS, EXPOSED
COPPER TRACES ARE PERMITTED OUTSIDE THE b1 PAD AREA.

JEDEC SOLID STATE PRODUCT OUTLINE Copyright © 2024 JEDEC	TITLE PLASTIC BOTTOM GRID ARRAY BALL, 0.60 MM X 0.50 MM PITCH RECTANGULAR FAMILY PACKAGE	NUMBER MO-363	ISSUE A	DATE JUL 2024	SHEET 7 OF 8
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NOTES CONTINUED:

15 FOR GLOB TOP AND FLIP CHIP CONFIGURATIONS, PARALLELISM (ccc) APPLIES ONLY TO THE SURFACE DIRECTLY ABOVE THE DIE AREA. THE PARALLELISM SPECIFICALLY WILL NOT APPLY TO ANY FILLET OR SLOPED REGION OF THE ENCAPSULANT.

16 SEE JESD30 FOR EXPLANATION OF VARIATION SCHEME.
PACKAGE HEIGHT IS THE MAXIMUM PACKAGE THICKNESS.

17. THE Z1 HEIGHT NEEDS TO BE ACCEPTABLE TO MANUFACTURING STANDARDS.

STP (3D) FILE RECORD

3D FILE NAMES MAY EXCEED LENGTH REQUIREMENTS FOR SOME SOFTWARE TOOLS.

STP FILE NAME	DATE	ITEM NUMBER
MO-363A_PBGA-B245[299]_I0p5-R8p2X12p4Z#-C0p30Z#	JUL 2024	11-1066

TASK GROUP CONTRIBUTORS

CHANGXIN MEMORY TECHNOLOGIES (CXMT)
MICRON TECHNOLOGY, INC

CHANGE RECORD

IF THE CHANGE INVOLVES ANY WORDS ADDED OR DELETED (EXCLUDING DELETION OF ACCIDENTALLY REPEATED WORDS), THE CHANGE IS TO BE INCLUDED BELOW. PUNCTUATION CHANGES MAY OR MAY NOT BE INCLUDED.

INITIAL ISSUE: A	DATE: JULY 2024	ITEM NUMBER: 11-1066
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CHANGE RECORD HISTORY:

ISSUE: -	DATE: -	ITEM NUMBER: -
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LOCATION	CHANGED FROM:	CHANGED TO: